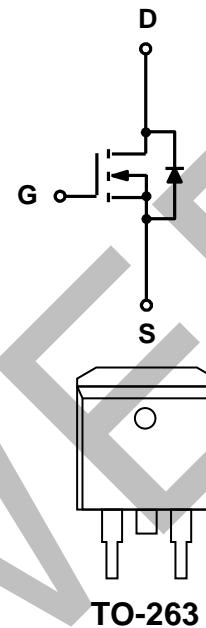


Features

- 30V,200A
 $R_{DS(ON)} < 1.8m\ \Omega @ V_{GS}=10V$ TYP:1.5m Ω
 $R_{DS(ON)} < 3.0m\ \Omega @ V_{GS}=4.5V$ TYP:2.5m Ω
- Advanced trench cell design
- Low Thermal Resistance

Applications

- Motor drivers
- DC - DC Converter



Package Marking and Ordering Information

Device Marking	Device	Device Package	Reel Size	Tape width	Quantity (PCS)
G018N03D	APG018N03D	TO-263	-	-	800

ABSOLUTE MAXIMUM RATINGS ($T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	30	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current ($T_a=25^\circ\text{C}$) ^(2,3)	I_D	200	A
Pulsed Drain Current ^(1,2,3)	I_{DM}	300	A
Single Pulsed Avalanche Energy ⁽²⁾	E_{AS}	240	mJ
Drain Power Dissipation	P_D	166	W
Thermal Resistance from Junction to Case ⁽²⁾	$R_{\theta JC}$	0.75	$^\circ\text{C/W}$
Thermal Resistance- Junction to Ambient ⁽²⁾	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$
Junction Temperature	T_J	150	$^\circ\text{C}$
Storage Temperature	T_{STG}	-55~ +150	$^\circ\text{C}$

Notes:

1. Pulse width $\leq 300\ \mu\text{s}$, duty cycle $\leq 2\ \%$
2. Surface Mounted on n 1 in2 pad area, $t \leq 10\ \text{sec}$.
3. Limited by bonding wire

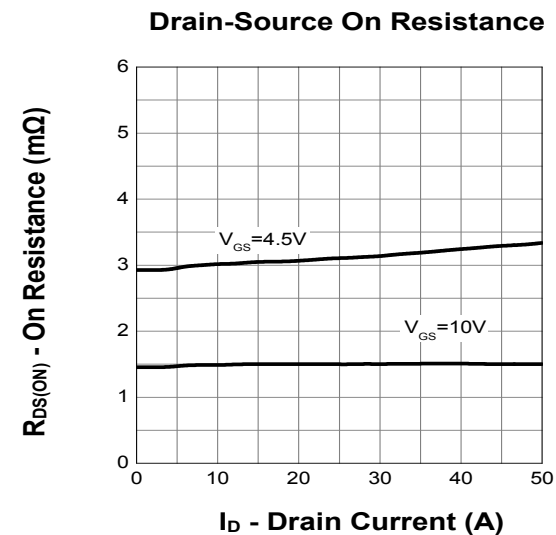
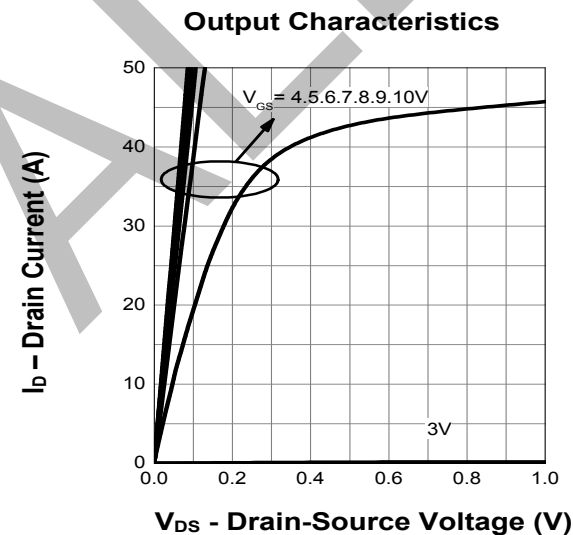
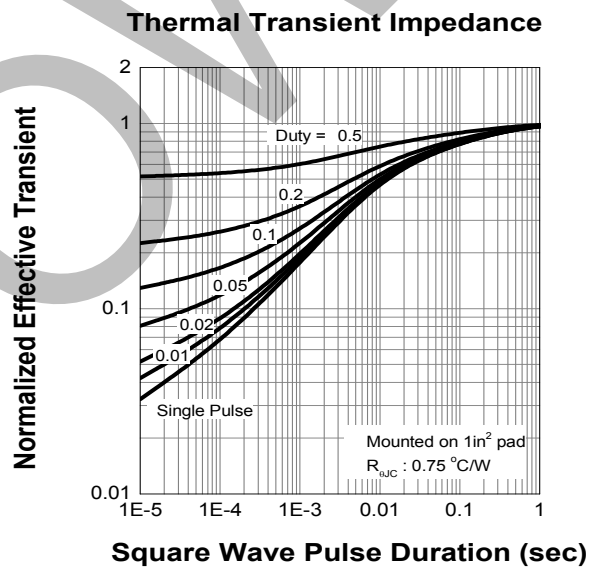
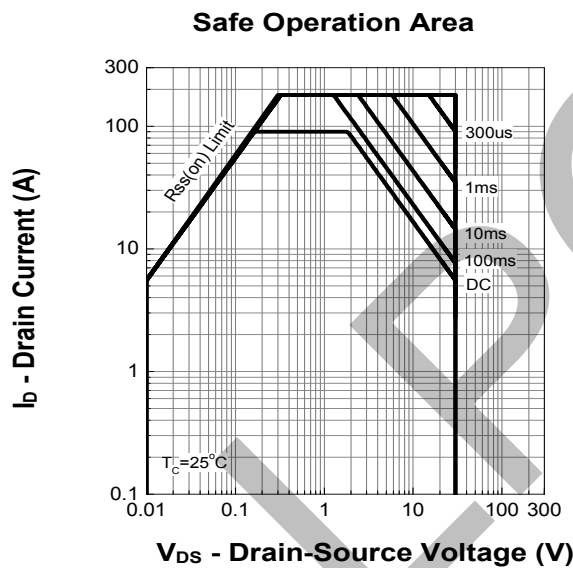
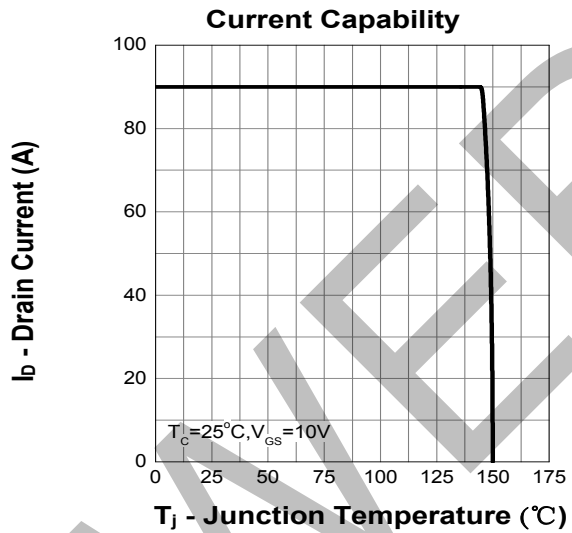
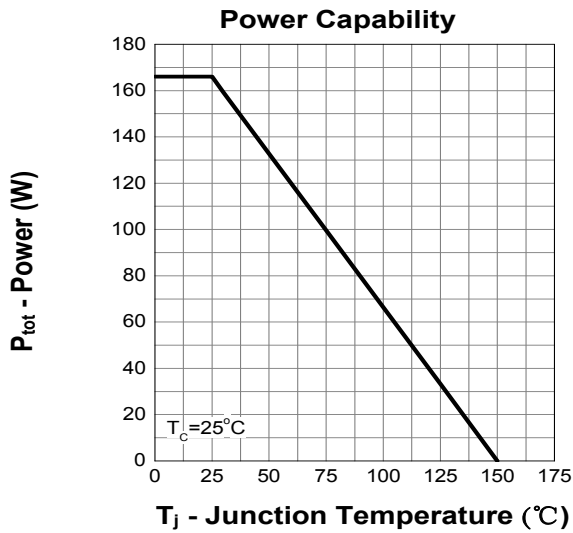
MOSFET ELECTRICAL CHARACTERISTICS(T_a=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Type	Max	Unit
Static Characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D =250μA	30	-	-	V
Zero gate voltage drain current	I _{DSS}	V _{DS} =24V, V _{GS} = 0V	-	-	1	μA
Gate-body leakage current	I _{GSS}	V _{GS} = ±20V, V _{DS} = 0V	-	-	±100	nA
Gate threshold voltage	V _{GS(th)}	V _{DS} =V _{GS} , I _D =250μA	1.5	-	2.5	V
Drain-source on-resistance ^(a)	R _{DS(on)}	V _{GS} =10V, I _D =20A	-	1.5	1.8	mΩ
		V _{GS} =4.5V, I _D =10A	-	2.5	3.0	mΩ
Dynamic characteristics						
Input Capacitance	C _{iss}	V _{DS} =15V, V _{GS} =0V, f =1.0MHz	-	10423	-	pF
Output Capacitance	C _{oss}		-	1181	-	
Reverse Transfer Capacitance	C _{rss}		-	343	-	
Switching characteristics						
Turn-on delay time	t _{d(on)}	V _{DD} =15V, I _D =20A, R _G =4.5Ω, R _L =0.75Ω, V _G =10V	-	33	-	ns
Turn-on rise time	t _r		-	88	-	
Turn-off delay time	t _{d(off)}		-	108	-	
Turn-off fall time	t _f		-	82	-	
Total Gate Charge	Q _g	V _{DS} =15V, I _D =20A, V _{GS} =10V	-	160	-	nC
Gate-Source Charge	Q _{gs}		-	45	-	
Gate-Drain Charge	Q _{gd}		-	27	-	
Source-Drain Diode characteristics						
Diode Forward voltage ^(a)	V _{SD}	T _J =25°C, V _{GS} =0V, I _S =20A	-	-	1.3	V
Diode Forward current	I _S	T _C =25°C	-	-	200	A
Body Diode Reverse Recovery Time	t _{rr}	T _J =25°C, I _F =20A, di/dt=100A/us		45		ns
Body Diode Reverse Recovery Charge	Q _{rr}	T _J =25°C, I _F =20A, di/dt=100A/us		44		uc

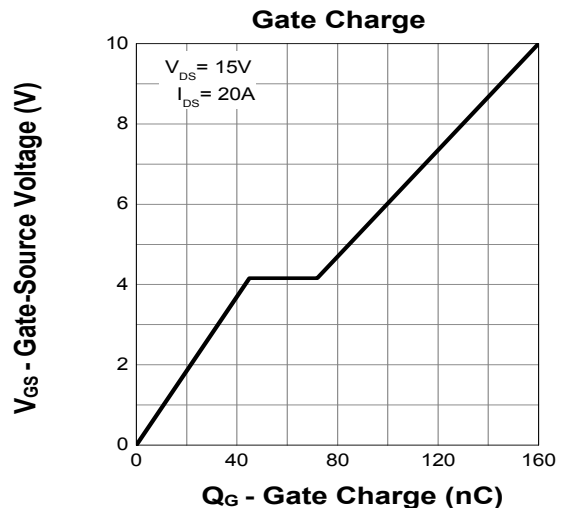
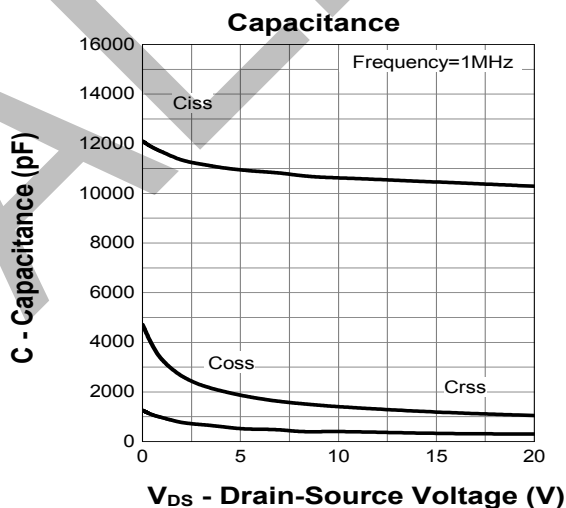
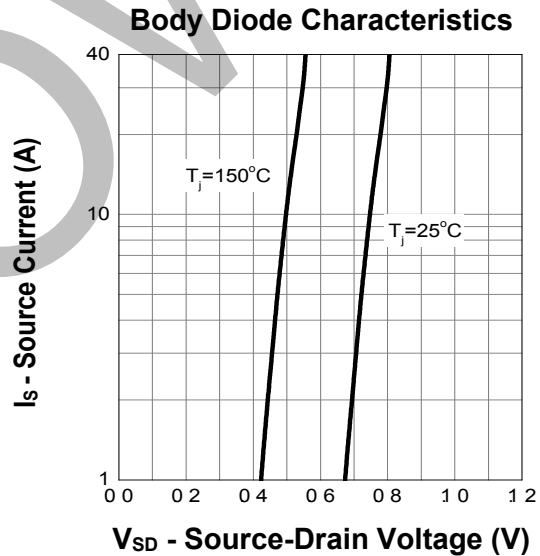
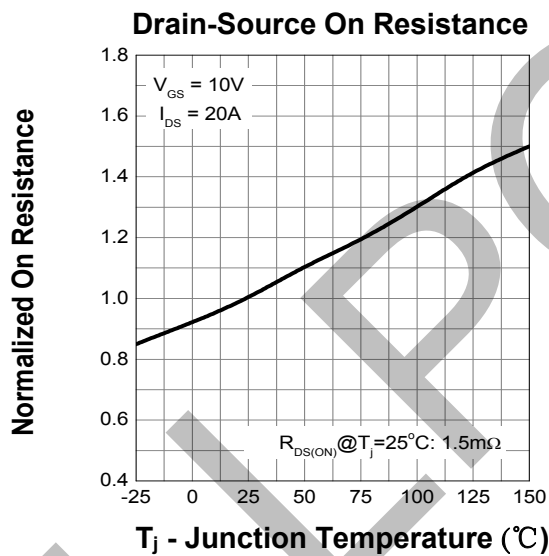
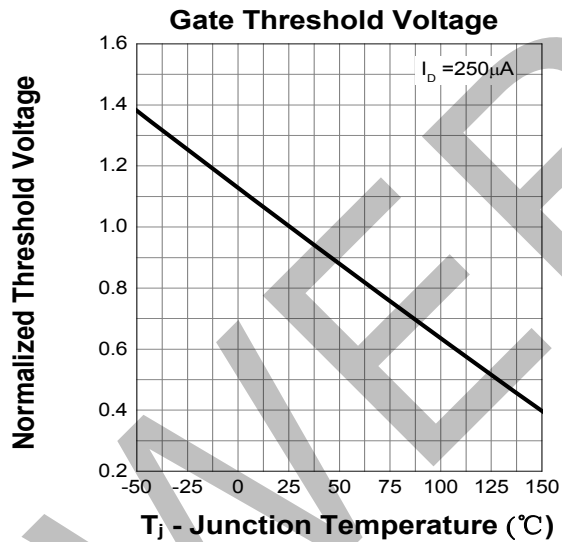
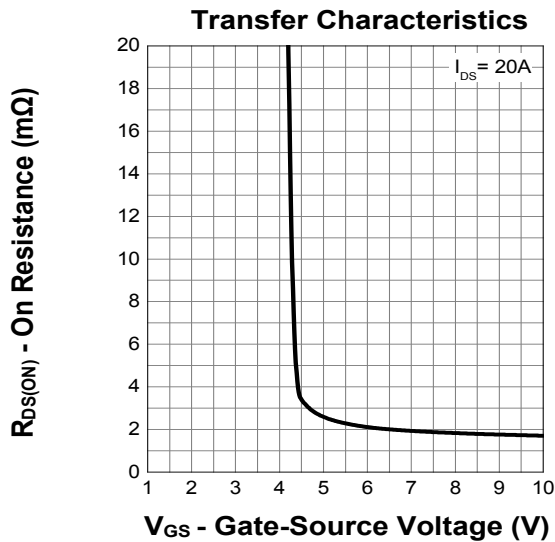
Notes:

- a) Pulse width ≤ 300 μs, duty cycle ≤ 2%
- b) Guaranteed by design, not subject to production testing

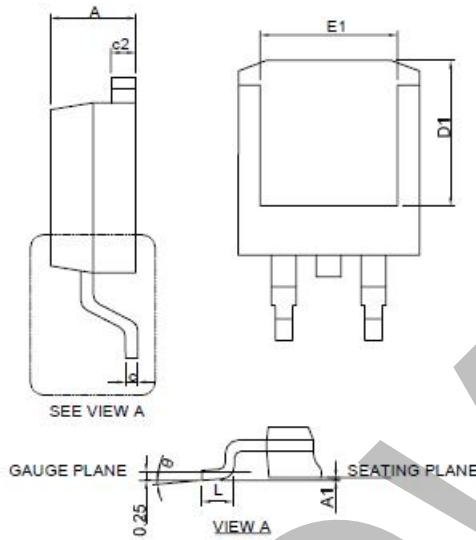
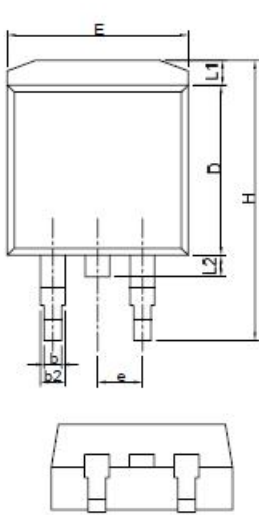
Typical Characteristics



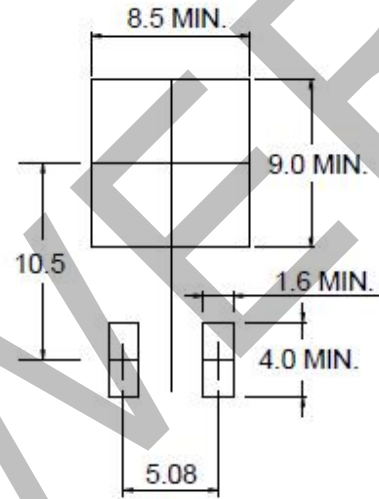
Typical Characteristics



Package Dimensions
TO-263



RECOMMENDED LAND PATTERN



Symbol	Dimensions In Millimeters	
	MIN.	MAX.
A	4.06	4.83
A1	0.00	0.25
b	0.51	0.99
b2	1.14	1.78
c	0.38	0.74
c2	1.14	1.65
D	8.38	9.65
D1	6.00	9.00
E	9.65	11.43
E1	6.22	9.00
e	2.54 BCS	
H	14.61	15.88
L	1.78	2.79
L1	-	1.68
L2	-	1.78
θ	0°	8°